

# 74HC7014-Q100

Hex non-inverting precision Schmitt-trigger

Rev. 1 — 26 May 2014

Product data sheet

## 1. General description

The 74HC7014-Q100 is a hex buffer with precision Schmitt-trigger inputs. The precisely defined trigger levels are lying in a window between  $0.55 \times V_{CC}$  and  $0.65 \times V_{CC}$ . It makes the circuit suitable to operate in a highly noisy environment. Input shorts are allowed to  $-1.5$  V and  $+16$  V without disturbing other channels. Inputs include clamp diodes that enable the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ . Schmitt trigger inputs transform slowly changing input signals into sharply defined jitter-free output signals.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40$  °C to  $+85$  °C and from  $-40$  °C to  $+125$  °C
- Operating voltage 3.0 V to 6.0 V
- Complies with JEDEC standard no. 7A
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0  $\Omega$ )

## 3. Applications

- Wave and pulse shapers for highly noisy environments

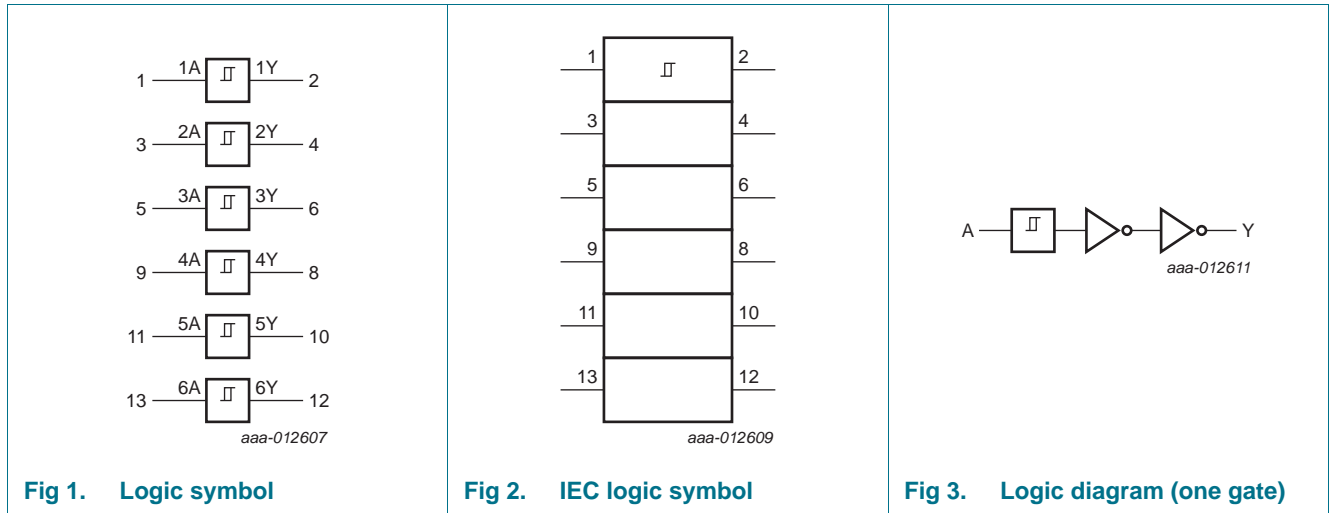
## 4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC7014D-Q100	$-40$ °C to $+125$ °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1

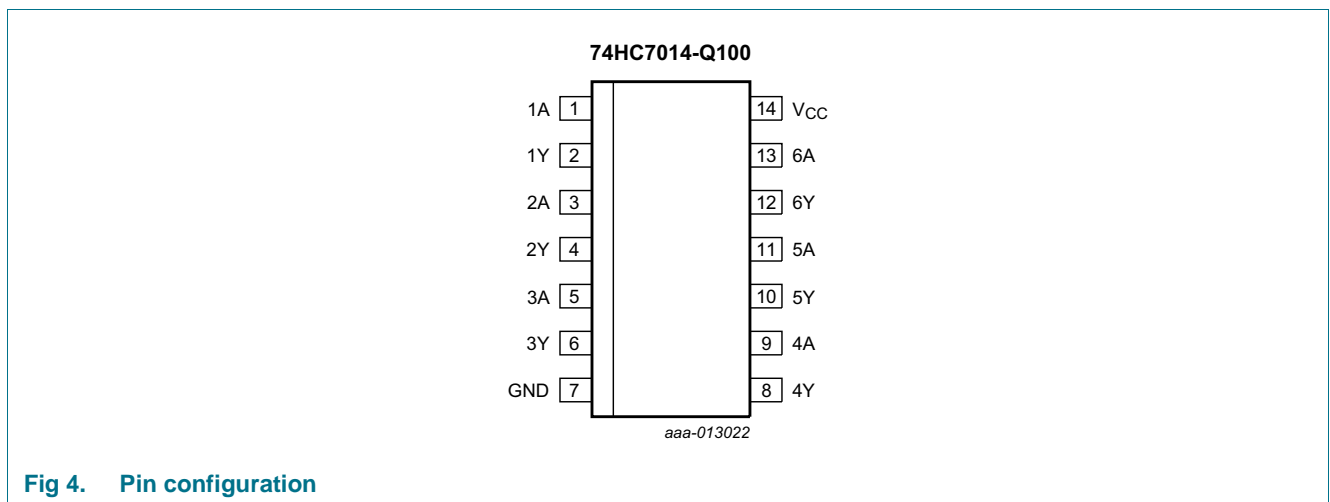


## 5. Functional diagram



## 6. Pinning information

### 6.1 Pinning



### 6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A to 6A	1, 3, 5, 9, 11, 13	data input
1Y to 6Y	2, 4, 6, 8, 10, 12	data output
GND	7	ground (0 V)
V <sub>CC</sub>	14	supply voltage

## 7. Functional description

Table 3. Functional table<sup>[1]</sup>

Input	Output
nA	nY
L	L
H	H

[1] H = HIGH voltage level; L = LOW voltage level

## 8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7	V
$I_{IK}$	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$ <sup>[1]</sup>	-	$\pm 20$	mA
$I_{OK}$	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$ <sup>[1]</sup>	-	$\pm 20$	mA
$I_O$	output current	$-0.5\text{ V} < V_O < V_{CC} + 0.5\text{ V}$	-	25	mA
$I_{CC}$	supply current		-	50	mA
$I_{GND}$	ground current		-50	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation		-	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO14 packages:  $P_{tot}$  derates linearly with 5.5 mW/K above 60 °C.

## 9. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		2.0	5.0	6.0	V
$V_I$	input voltage		0	-	$V_{CC}$	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	-	+125	°C

### 10. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I <sub>O</sub> = -5.2 mA; V <sub>CC</sub> = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I <sub>O</sub> = 5.2 mA; V <sub>CC</sub> = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>CC</sub> = 6.00 V; V <sub>I</sub> = V <sub>CC</sub> or GND	-	-	0.1	1.0	-	1.0	-	μA
		V <sub>CC</sub> = 3.00 V to 6.00 V; V <sub>I</sub> = 16 V or GND	-	-	0.5	5.0	-	5.0	-	μA
I <sub>CC</sub>	supply current	V <sub>CC</sub> = 3.00 V	-	0.7	1.4	-	1.8	-	2.1	mA
		V <sub>CC</sub> = 5.25 V	-	3.0	6.0	-	7.5	-	7.5	mA
		V <sub>CC</sub> = 6.00 V	-	3.7	7.4	-	10.0	-	13.0	mA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	pF	

## 11. Dynamic characteristics

**Table 7. Dynamic characteristics**  
*GND = 0 V; for test circuit, see Figure 6.*

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Max (85 °C)	Max (125 °C)	
t <sub>PHL</sub>	HIGH to LOW propagation delay	nA to nY; see <a href="#">Figure 5</a>						
		V <sub>CC</sub> = 3.00 V	-	95	475		715	ns
		V <sub>CC</sub> = 4.75 V	-	38	115	-	175	ns
		V <sub>CC</sub> = 6.00 V	-	27	73	93	112	ns
t <sub>PLH</sub>	LOW to HIGH propagation delay	nA to nY; see <a href="#">Figure 5</a>						
		V <sub>CC</sub> = 3.00 V	-	47	175	220	260	ns
		V <sub>CC</sub> = 4.75 V	-	23	52	65	78	ns
		V <sub>CC</sub> = 6.00 V	-	18	46	58	70	ns
t <sub>t</sub>	transition time	see <a href="#">Figure 5</a> <a href="#">[1]</a>						
		V <sub>CC</sub> = 3.00 V	-	12	20	25	30	ns
		V <sub>CC</sub> = 4.75 V	-	7	15	19	22	ns
		V <sub>CC</sub> = 6.00 V	-	6	13	16	19	ns
C <sub>PD</sub>	power dissipation capacitance	per gate; V <sub>I</sub> = GND to V <sub>CC</sub> <a href="#">[2]</a>	-	9	-	-	-	pF

[1] t<sub>t</sub> is the same as t<sub>THL</sub> and t<sub>TLH</sub>.

[2] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

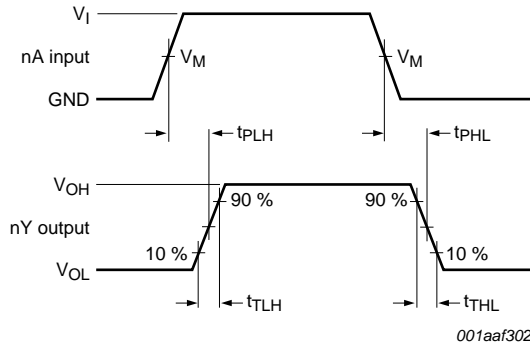
C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of outputs.

12. Waveforms

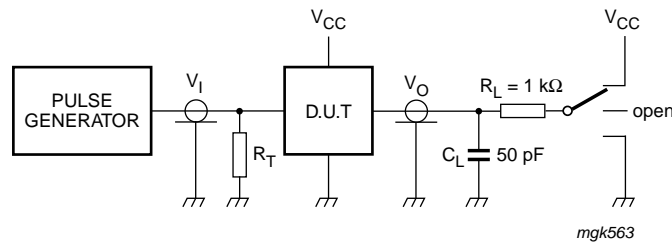


Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

Fig 5. The input (nA) to output (nY) propagation delays and output transition times

Table 8. Measurement points

Type	Input	Output
	$V_M$	$V_M$
74HC7014-Q100	$0.5V_{CC}$	$0.5V_{CC}$



Test data is given in [Table 9](#).  
 Definitions test circuit:  
 $R_L$  = Load resistance.  
 $C_L$  = Load capacitance including jig and probe capacitance.  
 $R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

Fig 6. Test circuit for measuring switching times

Table 9. Test data

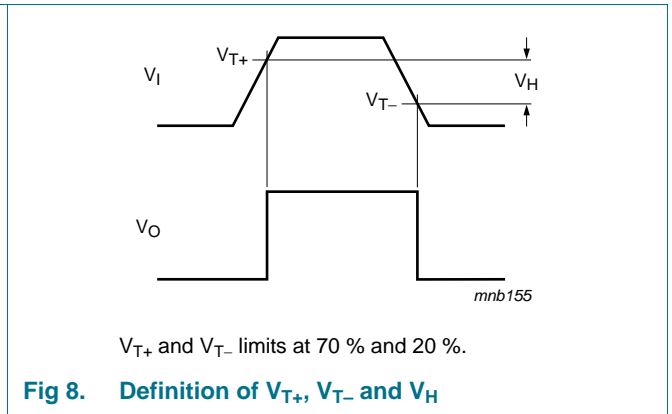
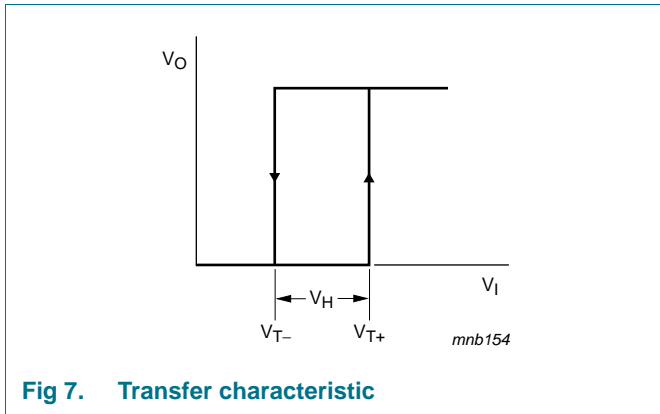
Type	Input	$t_r, t_f$	Test
	$V_I$		$t_{PHL}, t_{PLH}$
74HC7014-Q100	GND to $V_{CC}$	6 ns	open

### 13. Transfer characteristics

**Table 10. Transfer characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V); see [Figure 7](#) and [Figure 8](#).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>T+</sub>	positive-going threshold voltage	V <sub>CC</sub> = 3.00 V	-	1.86	1.95	-	1.95	-	1.95	V
		V <sub>CC</sub> = 4.75 V	-	2.94	3.08	-	3.08	-	3.08	V
		V <sub>CC</sub> = 5.00 V	-	3.10	3.25	-	3.25	-	3.25	V
		V <sub>CC</sub> = 5.25 V	-	3.25	3.41	-	3.41	-	3.41	V
		V <sub>CC</sub> = 6.00 V	-	3.72	3.90	-	3.90	-	3.90	V
V <sub>T-</sub>	negative-going threshold voltage	V <sub>CC</sub> = 3.00 V	1.65	1.74	-	1.65	-	1.65	-	V
		V <sub>CC</sub> = 4.75 V	2.62	2.76	-	2.62	-	2.62	-	V
		V <sub>CC</sub> = 5.00 V	2.75	2.90	-	2.75	-	2.75	-	V
		V <sub>CC</sub> = 5.25 V	2.89	3.05	-	2.89	-	2.89	-	V
		V <sub>CC</sub> = 6.00 V	3.30	3.48	-	3.30	-	3.30	-	V
V <sub>H</sub>	hysteresis voltage	V <sub>CC</sub> = 3.00 V	50	120	-	50	-	50	-	V
		V <sub>CC</sub> = 4.75 V	100	180	-	100	-	100	-	V
		V <sub>CC</sub> = 5.00 V	120	200	-	120	-	120	-	V
		V <sub>CC</sub> = 5.25 V	130	210	-	130	-	130	-	V
		V <sub>CC</sub> = 6.00 V	160	240	-	160	-	160	-	V



14. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

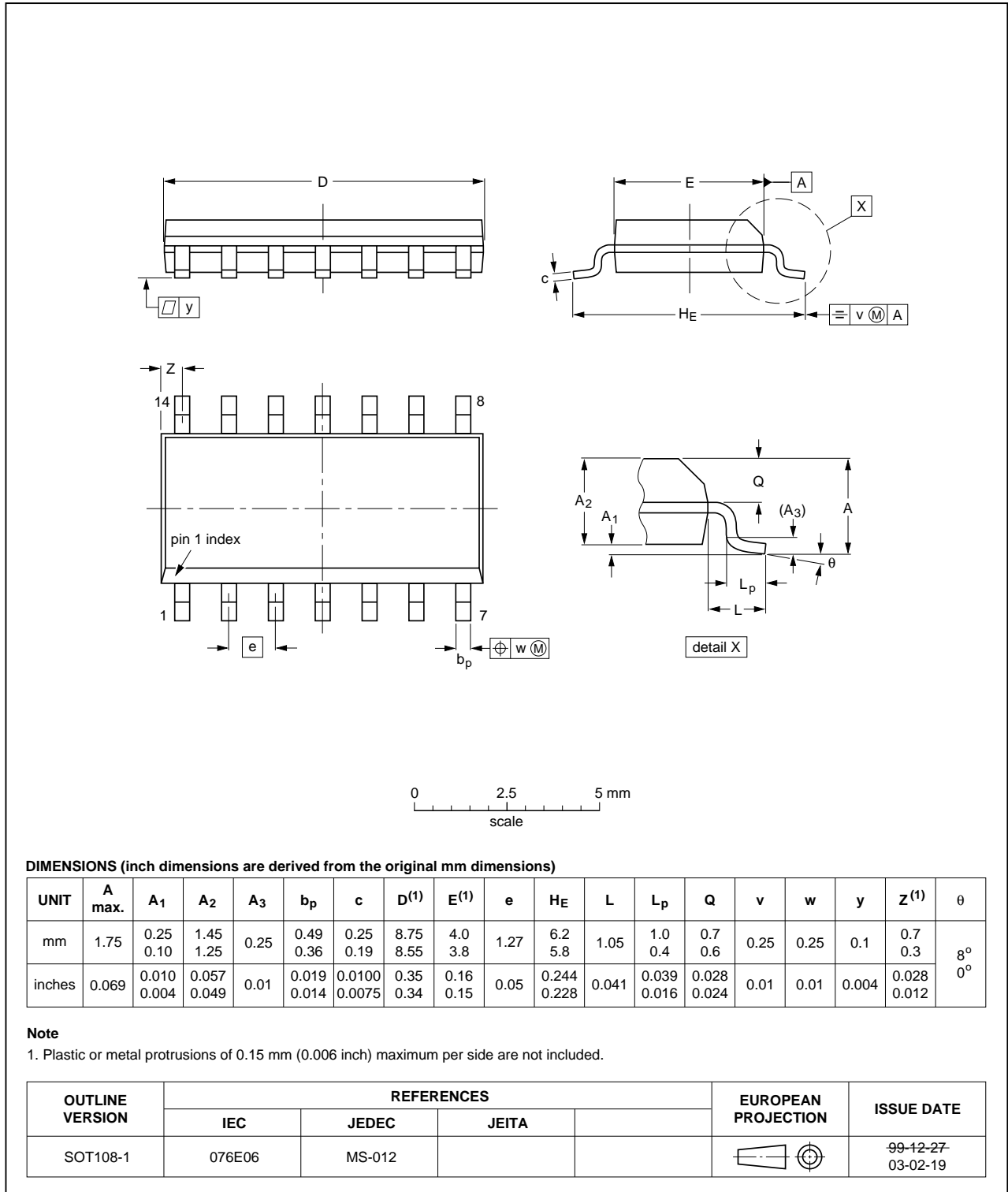


Fig 9. Package outline SOT108-1 (SO14)



## 15. Abbreviations

Table 11. Abbreviations

Acronym	Description
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MIL	Military
MM	Machine Model

## 16. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC7014_Q100 v.1	20140526	Product data sheet	-	-

## 17. Legal information

### 17.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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